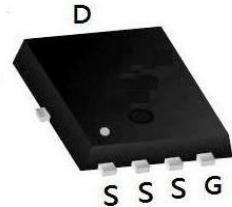


### Product Summary

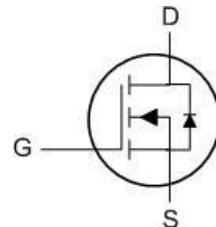
BVDSS	RDS(on)	ID
60V	2.4mΩ	125A



### Features

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low R<sub>DS(ON)</sub>

**PDFN5060-8L**



### Applications

- DC-DC Converters
- Power management functions
- Synchronous-rectification applications

### Absolute Maximum Ratings:

Symbol	Parameter	Value	Units
V <sub>DSS</sub>	Drain-to-Source Voltage	60	V
I <sub>D</sub>	Continuous Drain Current T <sub>C</sub> = 25 °C	125	A
	Continuous Drain Current T <sub>C</sub> = 100 °C	101	A
I <sub>DM</sub> <sup>a1</sup>	Pulsed Drain Current	641	A
E <sub>AS</sub> <sup>a2</sup>	Single pulse avalanche energy	189	mJ
V <sub>GS</sub>	Gate-to-Source Voltage	±20	V
P <sub>D</sub>	Power Dissipation	113	W
T <sub>J</sub> , T <sub>STG</sub>	Operating Junction and Storage Temperature Range	150, -55 to 150	°C
T <sub>L</sub>	Maximum Temperature for Soldering	260	°C

### Thermal Characteristics:

Symbol	Parameter	Value	Units
R <sub>θJC</sub>	Thermal Resistance, Junction-to-Case	1.11	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient	39.4	°C/W

**Electrical Characteristics (T<sub>c</sub> = 25°C unless otherwise specified) :**

Static Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
V <sub>DSS</sub>	Drain to Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	60	--	--	V
I <sub>DSS</sub>	Drain to Source Leakage Current	V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V	--	--	1	μA
I <sub>GSS(F)</sub>	Gate to Source Forward Leakage	V <sub>GS</sub> =+20V	--	--	100	nA
I <sub>GSS(R)</sub>	Gate to Source Reverse Leakage	V <sub>GS</sub> =-20V	--	--	-100	nA
V <sub>GS(TH)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> = 250μA	1.2	--	2.2	V
R <sub>DSS(ON)</sub>	Drain-to-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	--	2.4	2.9	mΩ

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V V <sub>DS</sub> = 30V f = 1.0MHz	--	4610	6915	pF
C <sub>oss</sub>	Output Capacitance		--	2188	3282	
C <sub>rss</sub>	Reverse Transfer Capacitance		--	66	132	
R <sub>g</sub>	Gate resistance		--	0.93	18.8	Ω

Resistive Switching Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
t <sub>d(ON)</sub>	Turn-on Delay Time	I <sub>D</sub> =40A V <sub>DS</sub> = 30V V <sub>GS</sub> = 10V R <sub>G</sub> = 2.7Ω	--	14.13	--	ns
t <sub>r</sub>	Rise Time		--	63.73	--	
t <sub>d(OFF)</sub>	Turn-Off Delay Time		--	46.8	--	
t <sub>f</sub>	Fall Time		--	105.07	--	
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> =10V V <sub>DS</sub> = 30V I <sub>D</sub> =40A	--	74.37	111.56	nC
Q <sub>gs</sub>	Gate Source Charge		--	17.26	--	
Q <sub>gd</sub>	Gate Drain Charge		--	9.44	18.88	

Source-Drain Diode Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
I <sub>S</sub>	Diode Forward Current	T <sub>C</sub> =25 °C	--	--	125	A
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =40A, V <sub>GS</sub> =0V	--	0.83	1.2	V
t <sub>rr</sub>	Reverse Recovery time	I <sub>S</sub> =40A, dI/dt=300A/μs	--	52.78	105.56	ns
Q <sub>rr</sub>	Reverse Recovery Charge		--	56.31	112.62	nC

<sup>a1</sup>: Repetitive rating; pulse width limited by maximum junction temperature <sup>a2</sup>:  
 VDD=30V, L=0.3mH, R<sub>g</sub>=25Ω, Starting TJ=25 °C

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## Typical Performance Characteristics

Fig 1: Output Characteristics

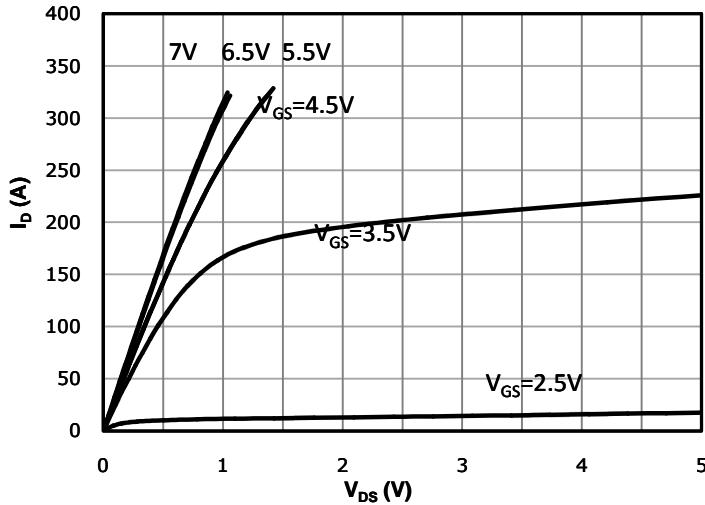


Fig 2: Transfer Characteristics

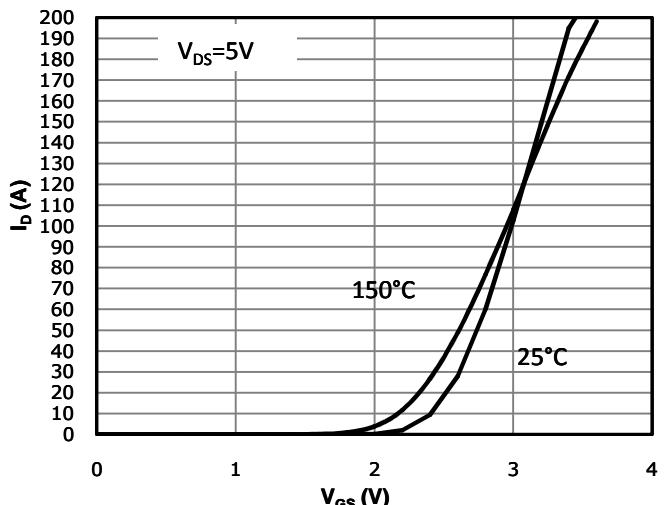


Fig 3:  $R_{DS(on)}$  vs Drain Current and Gate Voltage

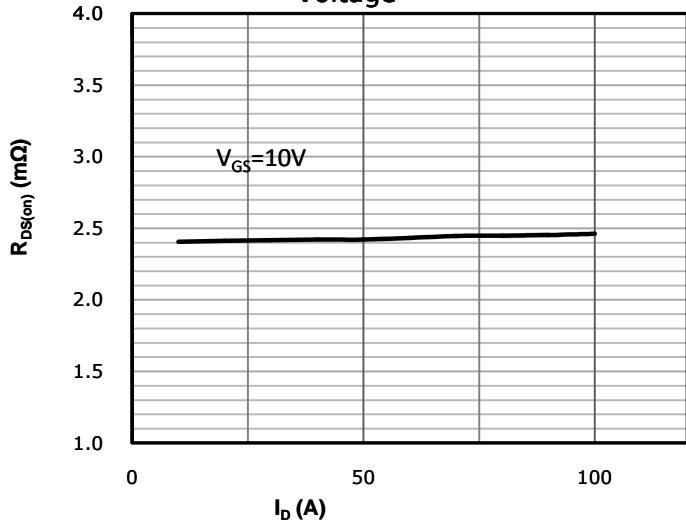


Fig 4:  $R_{DS(on)}$  vs Gate Voltage

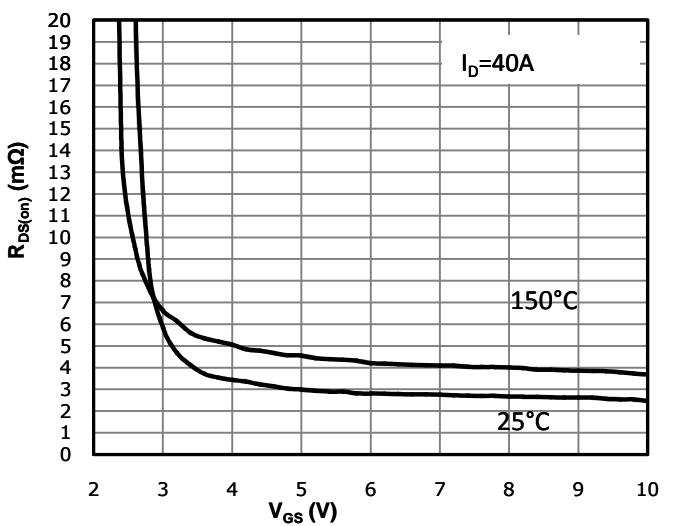


Fig 5:  $R_{DS(on)}$  vs. Temperature

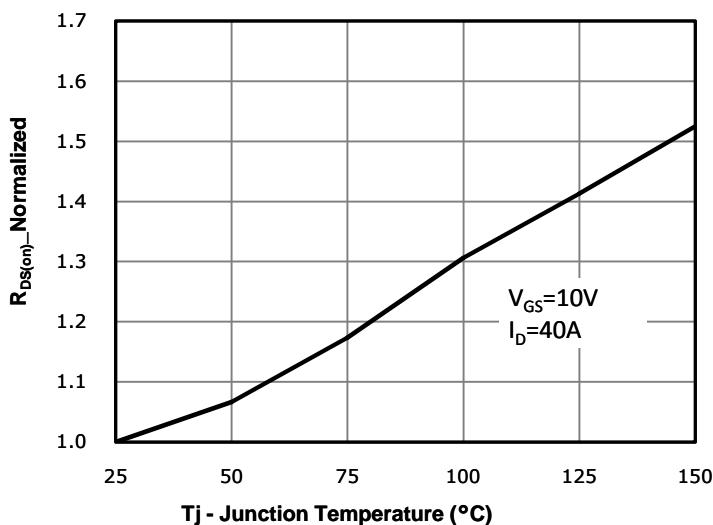
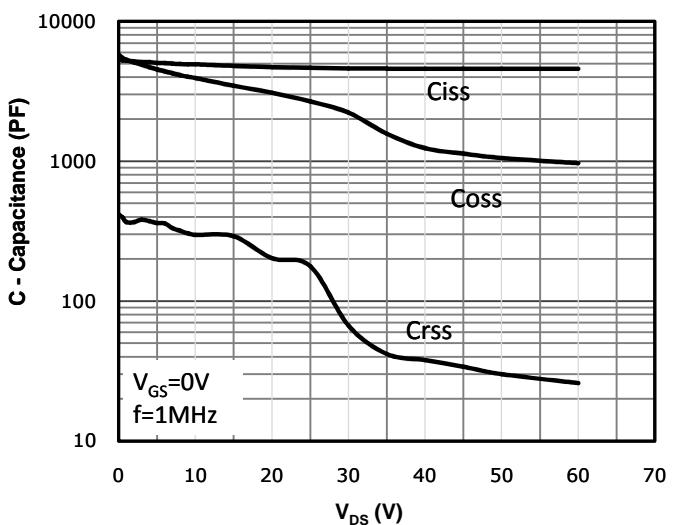


Fig 6: Capacitance Characteristics



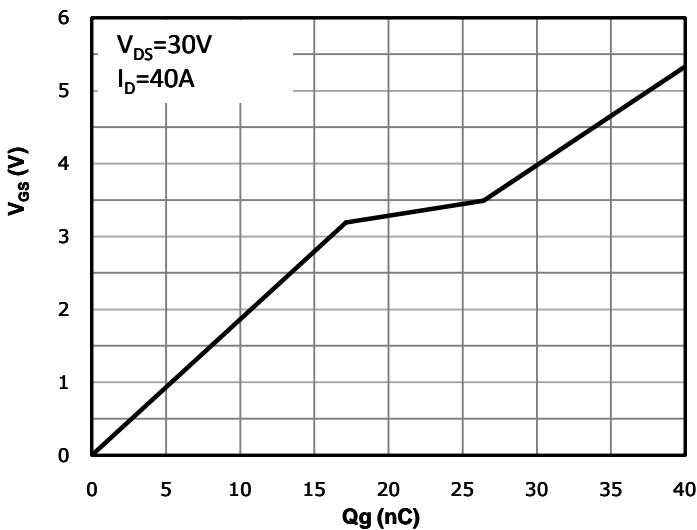
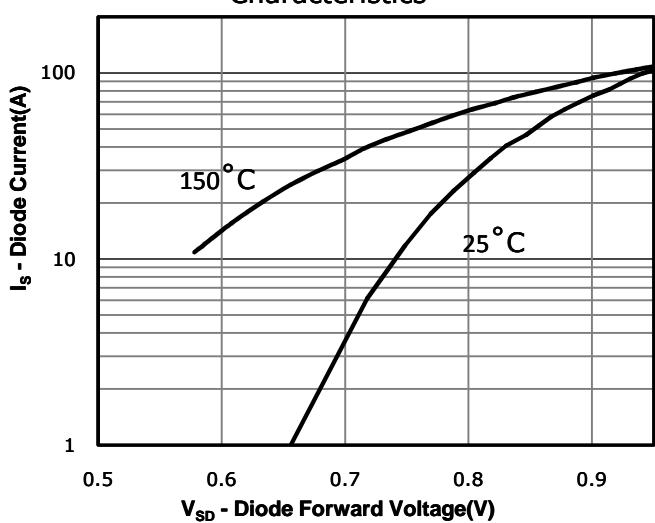
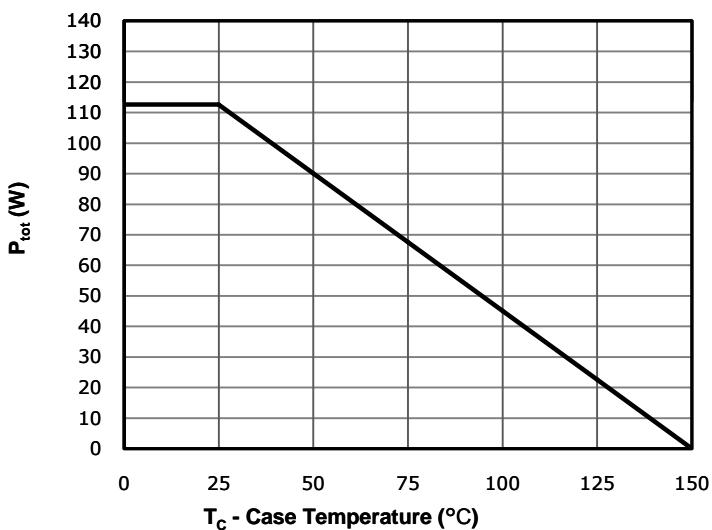
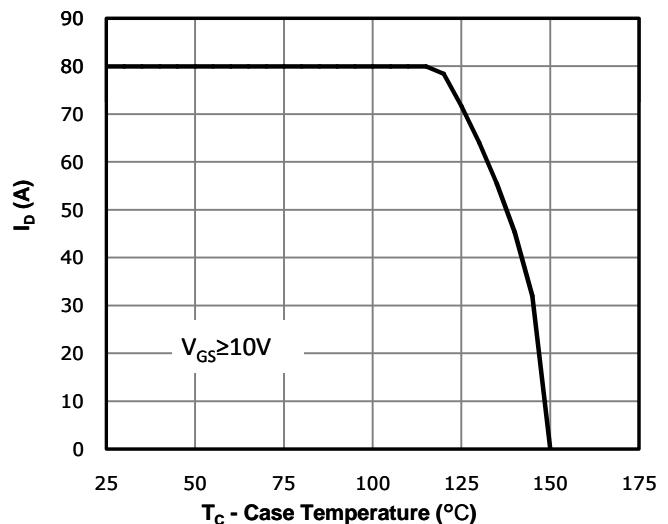
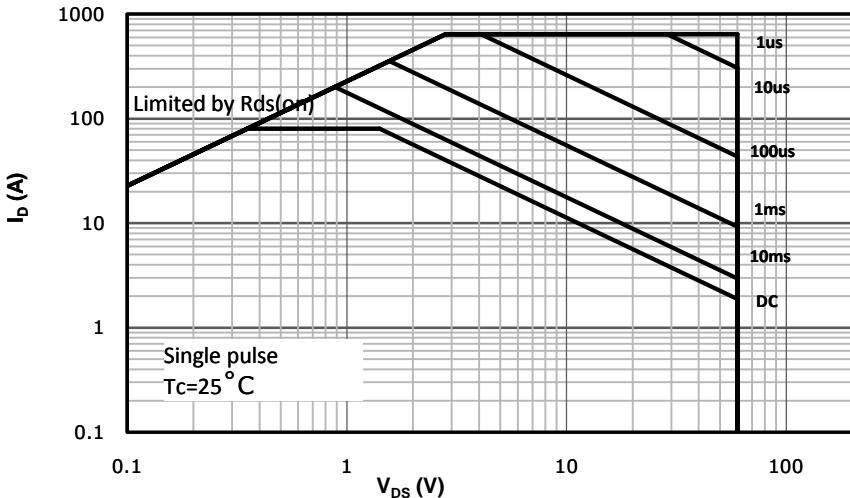
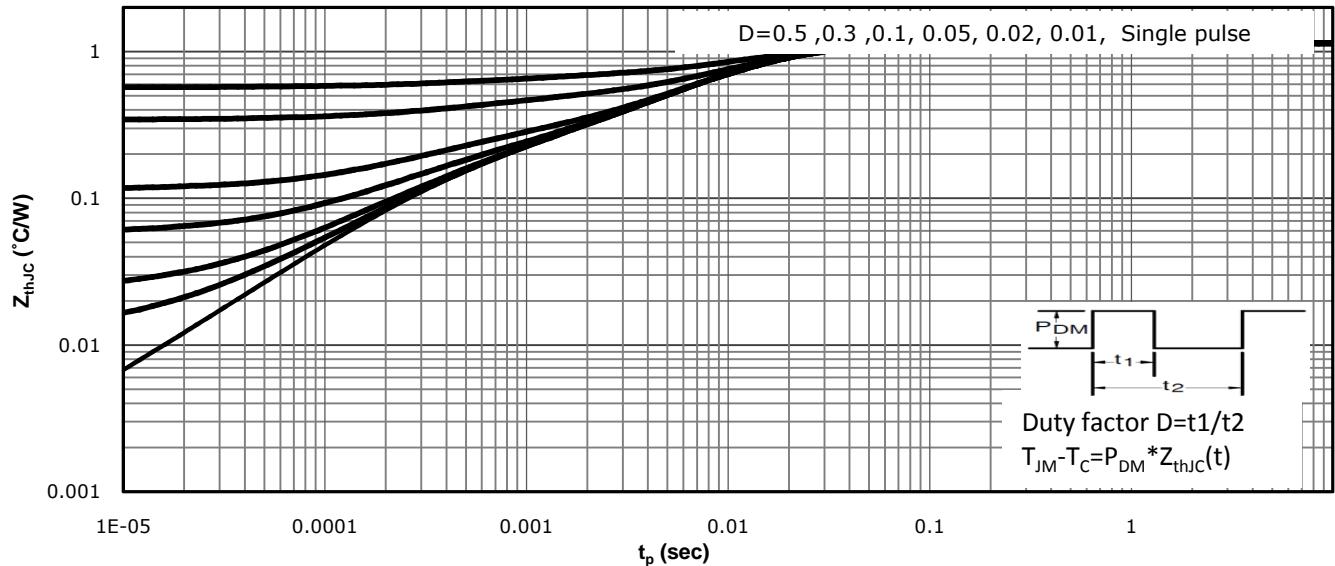
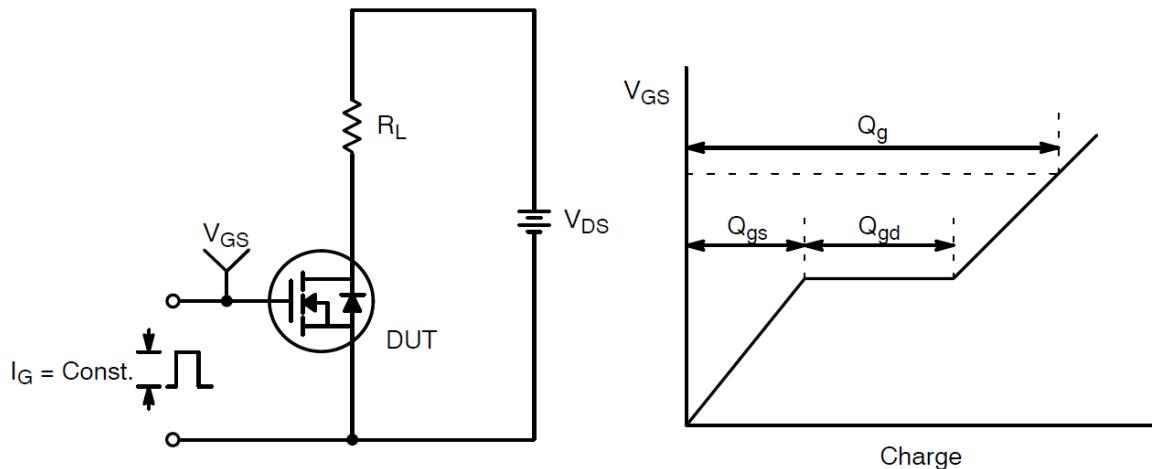
**Fig 7: Gate Charge Characteristics**

**Fig 8: Body-diode Forward Characteristics**

**Fig 9: Power Dissipation**

**Fig 10: Drain Current Derating**

**Fig 11: Safe Operating Area**


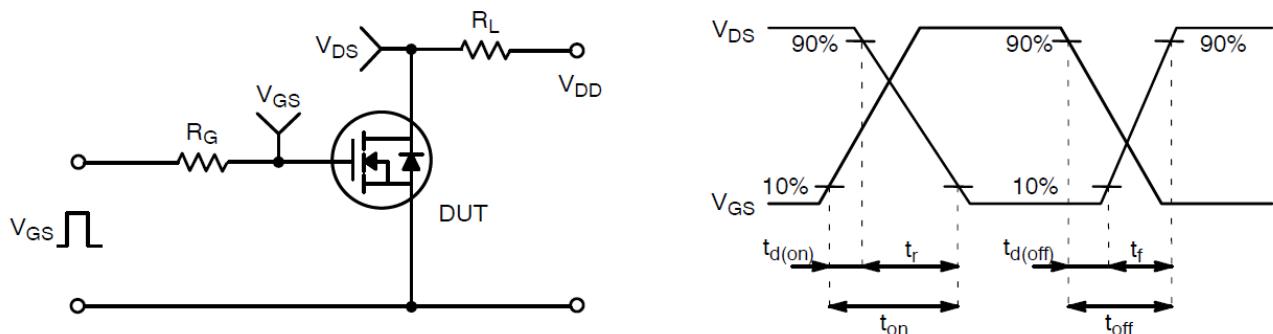
Fig 12: Max. Transient Thermal Impedance



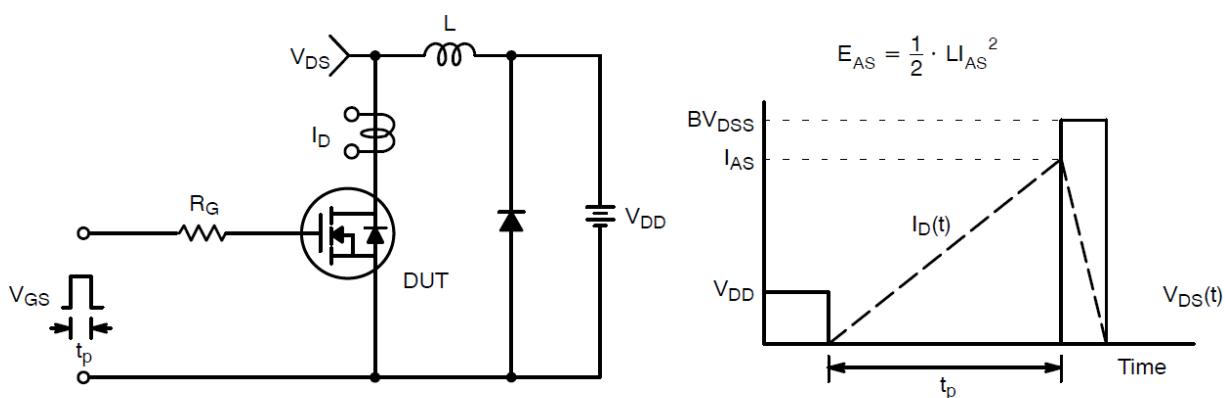
### Test Circuit and Waveform:



**Gate Charge Test Circuit & Waveform**



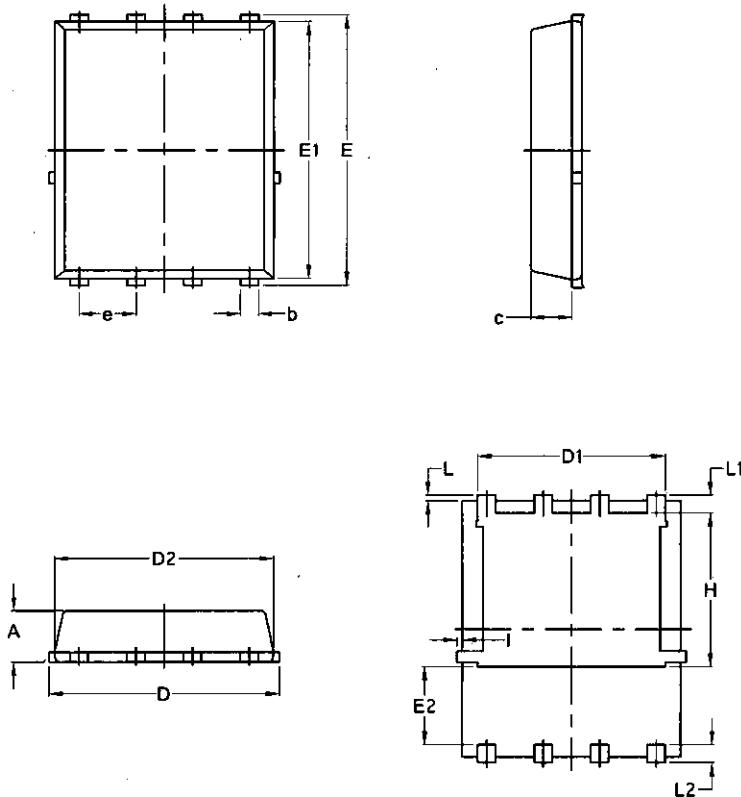
**Resistive Switching Test Circuit & Waveforms**



**Unclamped Inductive Switching Test Circuit & Waveforms**

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## Package Mechanical Data-PDFN5060-8L-Single



Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070